



PRODUCT CHANGE NOTICE

1. TITLE HFB25HJ20, Ultra-Fast Discrete Diode		2. DOCUMENT NUMBER FV5-C-11-004
		3. DATE February 23, 2011
4. MANUFACTURER AND ADDRESS International Rectifier 205 Crawford Street Leominster, MA 01453		5. MANUFACTURER PART NUMBER See below for IR Part Numbers
		6. BASE PART NA
		7. NATIONAL STOCK NUMBER (NSN) NA
8. CAGE 69210	9. EFFECTIVE DATE February 22, 2011	10. GOVERNMENT NUMBER NA
11. POINT OF CONTACT Manufacturer's Representative or Customer Service Representative (978) 534-5776		12. DRAWING NUMBER NA
		13. SPECIFICATION NUMBER MIL-PRF-19500
14. PRODUCT CHANGE This GIDEP PCN is to announce the addition of Toshiba XE13-B9144 (33-0275-06B) die coat to the following International Rectifier Part No. HFB25HJ20 HFB25HJ20SCS HFB25HJ20SCX HFB25HJ20SCV Description: 200V 25A Hi-Rel Ultra-Fast Discrete Diode in a SMD-0.5 package.  Reason for Change: Arcing can occur at high voltage as a result of surface charge build-up in the termination area. To prevent arcing, IR will apply a controlled amount of silicone based coating to the FRED die surface. The die coat acts as passivation to effectively suppress any arcing in the termination. This change will extend the die coat application from the 400V, where it is being used currently, to the 200V FRED product. Impact of Change: No effect to form, fit, or function. Additional package weight of less than 3mg. Qualification: As this process is qualified on higher voltage products, qualification is not required per MIL-PRF-19500. However, IR is performing GRP A, B, C, and E (partial) per MIL-PRF-19500 for internal validation.		
		16. APPROVING GOVERNMENT ACTIVITY
17. GIDEP REPRESENTATIVE Paul Hebert	18. SIGNATURE 	19. DATE February 23, 2011